

CLAIMS

What is claimed is:

SUB
A1

1. A method for sequencing a developer process to reduce wafer pattern defects, comprising:

5 dispensing a substantially inert material onto a wafer surface prior to dispensing developer fluid.

2. A method for sequencing a developer process to reduce wafer pattern defects, comprising:

A

10 inducing a flow of developer fluid across a portion of a wafer surface for a time interval greater than a transit time for a fluid element to reach an outer wafer edge, the time interval prior to the substantial completion of the developing chemical reaction.

3. A method for sequencing a developer process to reduce wafer pattern defects, comprising:

15 dispensing a fresh charge of developer fluid over the wafer after a developing chemical reaction has proceed substantially to completion.

B

SUB
B2

4. The method of claim 3 further comprising:

dispensing a substantially inert material over a wafer subsequent to dispensing the fresh charge of developer fluid.

B

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Add
B3

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